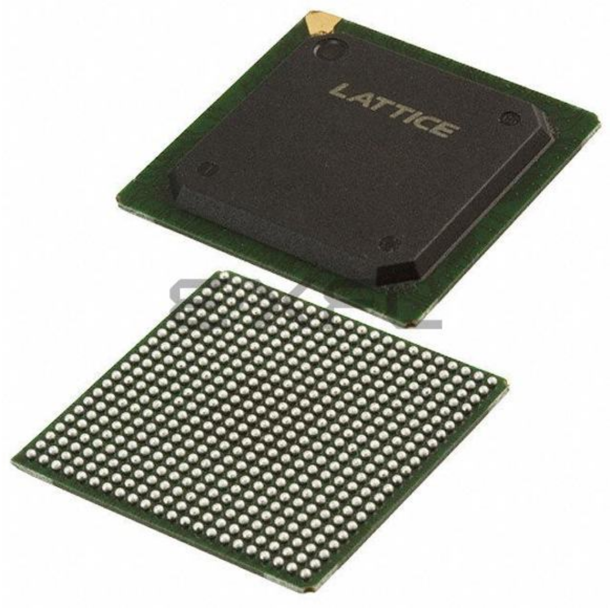
Lattice Semiconductor Corporation - LC51024MV-75FN484I Datasheet



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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	32
Number of Macrocells	1024
Number of Gates	-
Number of I/O	317
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc51024mv-75fn484i

Lattice Semiconductor Corporation

ispXPLD™ 5000MX Family

3.3V, 2.5V and 1.8V In-System Programmable
eXpanded Programmable Logic Device XPLD™ Family

February 2010 **Data Sheet**

Features

■ Flexible Multi-Function Block (MFB) Architecture

- SuperWIDE™ logic (up to 136 inputs)
- Arithmetic capability
- Single- or Dual-port SRAM
- FIFO
- Ternary CAM

■ sysCLOCK™ PLL Timing Control

- Multiply and divide between 1 and 32
- Clock shifting capability
- External feedback capability

■ sysIO™ Interfaces

- LVCMOS 1.8, 2.5, 3.3V
  - Programmable impedance
  - Hot-socketing
  - Flexible bus-maintenance (Pull-up, pull-down, bus-keeper, or none)
  - Open drain operation
- SSTL 2, 3 (I & II)
- HSTL (I, III, IV)
- PCI 3.3
- GTL+
- LVDS
- LVPECL
- LVTTL

■ Expanded In-System Programmability (ispXP™)

- Instant-on capability
- Single chip convenience
- In-System Programmable via IEEE 1532 Interface
- Infinitely reconfigurable via IEEE 1532 or sysCONFIG™ microprocessor interface
- Design security

■ High Speed Operation

- 4.0ns pin-to-pin delays, 300MHz f_{MAX}
- Deterministic timing

■ Low Power Consumption

- Typical static power: 20 to 50mA (1.8V), 30 to 60mA (2.5/3.3V)
- 1.8V core for low dynamic power

■ Easy System Integration

- 3.3V (5000MV), 2.5V (5000MB) and 1.8V (5000MC) power supply operation
- 5V tolerant I/O for LVCMOS 3.3 and LVTTL interfaces
- IEEE 1149.1 interface for boundary scan testing
- sysIO quick configuration
- Density migration
- Multiple density and package options
- PQFP and fine pitch BGA packaging
- Lead-free package options

Table 1. ispXPLD 5000MX Family Selection Guide

	ispXPLD 5256MX	ispXPLD 5512MX	ispXPLD 5768MX	ispXPLD 51024MX
Macrocells	256	512	768	1,024
Multi-Function Blocks	8	16	24	32
Maximum RAM Bits	128K	256K	384K	512K
Maximum CAM Bits	48K	96K	144K	192K
sysCLOCK PLLs	2	2	2	2
t_{PD} (Propagation Delay)	4.0ns	4.5ns	5.0ns	5.2ns
t_S (Register Set-up Time)	2.2ns	2.8ns	2.8ns	3.0ns
t_{CO} (Register Clock to Out Time)	2.8ns	3.0ns	3.2ns	3.7ns
f_{MAX} (Maximum Operating Frequency)	300MHz	275MHz	250MHz	250MHz
Functional Gates	75K	150K	225K	300K
I/Os	141	149/193/253	193/317	317/381
Packages	256 fpBGA	208 PQFP 256 fpBGA 484 fpBGA	256 fpBGA 484 fpBGA	484 fpBGA 672 fpBGA

Pseudo Dual-Port SRAM Mode

In Pseudo Dual-Port SRAM Mode the multi-function array is configured as a SRAM with an independent read and write ports that access the same 16,384-bits of memory. Data widths of 1, 2, 4, 8, 16 and 32 are supported by the MFB. Figure 10 shows the block diagram of the Pseudo Dual-Port SRAM.

Write data, write address, chip select and write enable signals are always synchronous (registered). The read data and read address signals can be synchronous or asynchronous. Reset is asynchronous. All write signals share the same clock, and clock enable. All read signals share the same clock and clock enable. Reset is shared by both read and write signals. Table 6 shows the possible sources for the clock, clock enable and initialization signals for the various registers.

Figure 10. Pseudo Dual-Port SRAM Block Diagram

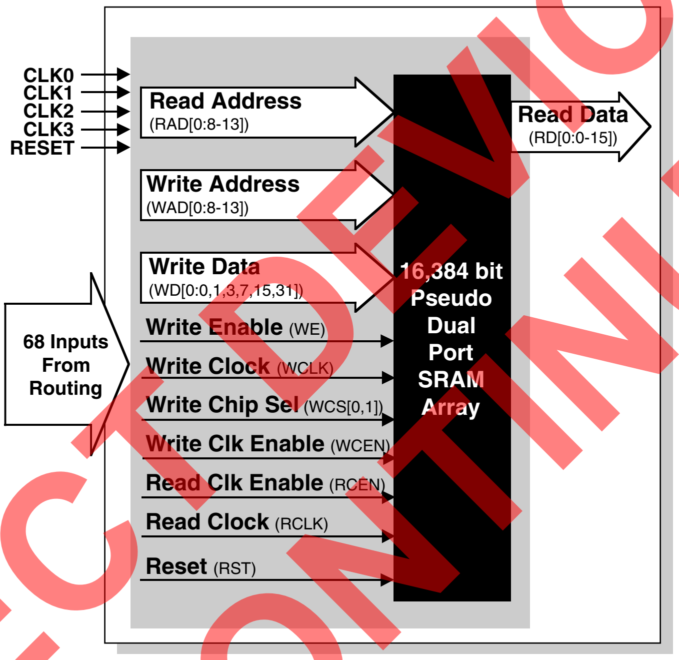

Table 6. Register Clock, Clock Enable, and Reset in Pseudo Dual-Port SRAM Mode

Register	Input	Source
Write Address, Write Data, Write Enable, and Write Chip Select	Clock	WCLK or one of the global clocks (CLK0 - CLK3). The selected signal can be inverted if desired.
	Clock Enable	WCEN or one of the global clocks (CLK1 - CLK2). The selected signal can be inverted if desired.
	Reset	Created by the logical OR of the global reset signal and RST. RST may have inversion if desired.
Read Data and Read Address	Clock	RCLK or one of the global clocks (CLK0 - CLK3). The selected signal can be inverted if desired.
	Clock Enable	RCEN or one of the global clocks (CLK1 - CLK2). The selected signal can be inverted if desired.
	Reset	Created by the logical OR of the global reset signal and RST. RST may have inversion if desired.

FIFO Mode

In FIFO Mode the multi-function array is configured as a FIFO (First In First Out) buffer with built in control. The read and write clocks can be different or the same dependent on the application. Four flags show the status of the FIFO; Full, Empty, Almost Full, and Almost Empty. The thresholds for Full, Almost full and Almost empty are programmable by the user. It is possible to reset the read pointer, allowing support of frame retransmit in communications applications. If desired, the block can be used in show ahead mode allowing the early reading of the next read address.

In this mode one ports accesses 16,384-bits of memory. Data widths of 1, 2, 4, 8, 16 and 32 are supported by the MFB. Figure 12 shows the block diagram of the FIFO.

Write data, write enable, flag outputs and read enable are synchronous. The Write Data, Almost Full and Full share the same clock and clock enables. Read outputs are synchronous although these can be configured in look ahead mode. The Read Data, Empty and Almost Empty signals share the same clock and clock enables. Reset is shared by all signals. Table 8 shows the possible sources for the clock, clock enable and reset signals for the various registers.

Figure 12. FIFO Block Diagram

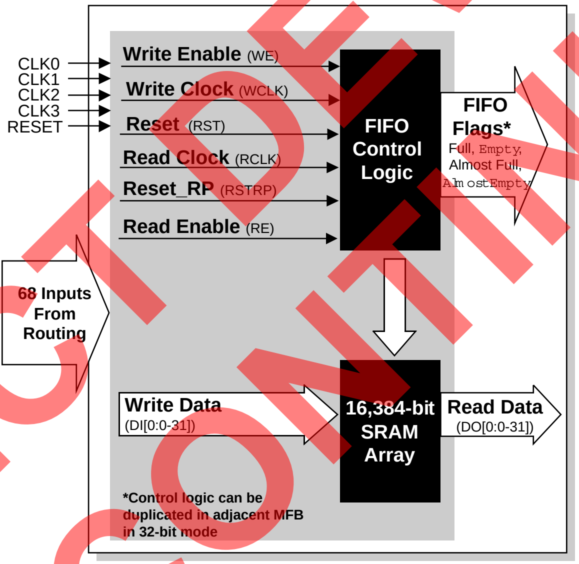

Table 8. Register Clocks, Clock Enables, and Initialization in FIFO Mode

Register	Input	Source
Write Data, Write Enable	Clock	WCLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	WE or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	N/A
Full and Almost Full Flags	Clock	WCLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	WE or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired.
Read Data, Empty and Almost Empty Flags	Clock	RCLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	RE or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired.

CAM Mode

In CAM Mode the multi-function array is configured as a Ternary Content Addressable Memory (CAM). CAM behaves like a reverse memory where the input is data and the output is an address. It can be used to perform a variety of high-performance look-up functions. As such, CAM has two modes of operation. In write or update mode the CAM behaves as a RAM and data is written to the supplied address. In read or compare operations data is supplied to the CAM and if this matches any of the data in the array the Match and Multiple Match (if there is more than one match) flags are set to true and the lowest address with matching data is output. The CAM contains 128 entries of 48 bits. Figure 13 shows the block diagram of the CAM.

To further enhance the flexibility of the CAM a mask register is available. If enabled during updates, bits corresponding with those set to 1 in the mask register are not updated. If enabled during compare operations, bits corresponding to those set to 1 in the mask register are not included in the compare. A write don't care signal allows don't cares to be programmed into the CAM if desired. Like other write operations the mask register controls this.

The write/comp data, write address, write enable, write chip select, and write don't care signals are synchronous. The CAM Output signals, match flag, and multimatch flag can be synchronous or asynchronous. The Enable mask register input is not latched but must meet setup and hold times relative to the write clock. All inputs must use the same clock and clock enable signals. All outputs must use the same clock and clock enable signals. Reset is common for both inputs and outputs. Table 9 shows the allowable sources for clock, clock enable, and reset for the various CAM registers.

Figure 13. CAM Mode

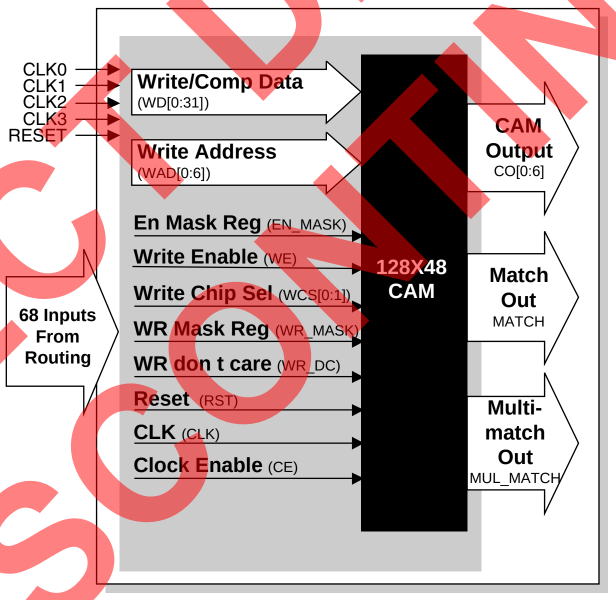

Table 9. Register Clocks, Clock Enables, and Initialization in CAM Mode

Register	Input	Source
Write data, Write address, Enable mask register, Write enable, write chip select, and write don't care, CAM Output, Match, and Multimatch	Clock	CLK or one of the global clocks (CLK0 - CLK3). Each of these signals can be inverted if required.
	Clock Enable	WE or one of the global clocks (CLK1 - CLK 2). Each of these signals can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RST. RST is routed by the multifunction array from GRP, with inversion if desired

sysCONFIG Interface

In addition to being able to program the device through the IEEE 1532 interface a microprocessor style interface (sysCONFIG interface) allows reconfiguration of the SRAM bits within the device. For more information on the sysCONFIG capability, refer to TN1026, ispXP Configuration Usage Guidelines.

Security Scheme

A programmable security scheme is provided on the ispXPLD 5000MX devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit prevents readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. The security bit also prevents programming and verification. The entire device must be erased in order to erase the security bit.

Low Power Consumption

The ispXPLD 5000MX devices use zero power non-volatile cells along with full CMOS design to provide low static power consumption. The 1.8V core reduces dynamic power consumption compared with devices with higher core voltages. For information on estimating power consumption, refer to TN1031 Power Estimation in ispXPLD 5000MX Devices.

Density Migration

The ispXPLD 5000MX family has been designed to ensure that different density devices in the same package have compatible pin-outs. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispXPLD 5000MX devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic notes. Internal boundary scan registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for board-level testing. The test access port has its own supply voltage and can operate with LVCMOS3.3, 2.5 and 1.8V standards.

sysIO Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os' physical nature should be minimal so that board test time is minimized. The ispXPLD 5000MX family of devices allows this by offering the user the ability to quickly configure the physical nature of the sysIO cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM™ System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

Supply Current

Symbol	Parameter	Condition	Min.	Typ.[3]	Max.	Units
ispXPLD 5256						
I_{CC}[1,2]	Operating Power Supply Current	V_{CC} = 3.3V, f = 1.0MHz	—	26	—	mA
		V_{CC} = 2.5V, f = 1.0MHz	—	26	—	mA
		V_{CC} = 1.8V, f = 1.0MHz	—	16	—	mA
I_{CCO}	Standby Power Supply Current (per I/O Bank)	V_{CCO} = 3.3V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 2.5V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 1.8V, f = 1.0MHz, unloaded	—	3	—	mA
I_{CCP}	PLL Power Supply Current (per PLL Bank)	V_{CCP} = 3.3V, f = 10MHz	—	11	—	mA
		V_{CCP} = 2.5V, f = 10MHz	—	11	—	mA
		V_{CCP} = 1.8V, f = 10MHz	—	3	—	mA
I_{CCJ}	Standby IEEE 1149.1 TAP Power Supply Current	V_{CCJ} = 3.3V	—	1	—	mA
		V_{CCJ} = 2.5V	—	1	—	mA
		V_{CCJ} = 1.8V	—	1	—	mA
ispXPLD 5512						
I_{CC}[1,2]	Operating Power Supply Current	V_{CC} = 3.3V, f = 1.0MHz	—	33	—	mA
		V_{CC} = 2.5V, f = 1.0MHz	—	33	—	mA
		V_{CC} = 1.8V, f = 1.0MHz	—	22	—	mA
I_{CCO}	Standby Power Supply Current (per I/O Bank)	V_{CCO} = 3.3V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 2.5V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 1.8V, f = 1.0MHz, unloaded	—	3	—	mA
I_{CCP}	PLL Power Supply Current (per PLL Bank)	V_{CCP} = 3.3V, f = 10MHz	—	11	—	mA
		V_{CCP} = 2.5V, f = 10MHz	—	11	—	mA
		V_{CCP} = 1.8V, f = 10MHz	—	3	—	mA
I_{CCJ}	Standby IEEE 1149.1 TAP Power Supply Current	V_{CCJ} = 3.3V	—	1	—	mA
		V_{CCJ} = 2.5V	—	1	—	mA
		V_{CCJ} = 1.8V	—	1	—	mA
ispXPLD 5768						
I_{CC}[1,2]	Operating Power Supply Current	V_{CC} = 3.3V, f = 1.0MHz	—	40	—	mA
		V_{CC} = 2.5V, f = 1.0MHz	—	40	—	mA
		V_{CC} = 1.8V, f = 1.0MHz	—	30	—	mA
I_{CCO}	Standby Power Supply Current (per I/O Bank)	V_{CCO} = 3.3V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 2.5V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 1.8V, f = 1.0MHz, unloaded	—	3	—	mA
I_{CCP}	PLL Power Supply Current (per PLL Bank)	V_{CCP} = 3.3V, f = 10MHz	—	11	—	mA
		V_{CCP} = 2.5V, f = 10MHz	—	11	—	mA
		V_{CCP} = 1.8V, f = 10MHz	—	3	—	mA
I_{CCJ}	Standby IEEE 1149.1 TAP Power Supply Current	V_{CCJ} = 3.3V	—	1	—	mA
		V_{CCJ} = 2.5V	—	1	—	mA
		V_{CCJ} = 1.8V	—	1	—	mA

Supply Current (Continued)

Symbol	Parameter	Condition	Min.	Typ.[3]	Max.	Units
ispXPLD 51024						
I_{CC}[1,2]	Operating Power Supply Current	V_{CC} = 3.3V, f = 1.0MHz	—	75	—	mA
		V_{CC} = 2.5V, f = 1.0MHz	—	75	—	mA
		V_{CC} = 1.8V, f = 1.0MHz	—	55	—	mA
I_{CCO}	Standby Power Supply Current (per I/O Bank)	V_{CCO} = 3.3V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 2.5V, f = 1.0MHz, unloaded	—	4	—	mA
		V_{CCO} = 1.8V, f = 1.0MHz, unloaded	—	3	—	mA
I_{CCP}	PLL Power Supply Current (per PLL Bank)	V_{CCP} = 3.3V, f = 10MHz	—	11	—	mA
		V_{CCP} = 2.5V, f = 10MHz	—	11	—	mA
		V_{CCP} = 1.8V, f = 10MHz	—	3	—	mA
I_{CCJ}	Standby IEEE 1149.1 TAP Power Supply Current	V_{CCJ} = 3.3V	—	1	—	mA
		V_{CCJ} = 2.5V	—	1	—	mA
		V_{CCJ} = 1.8V	—	1	—	mA

1. Device configured with 16-bit counters.
2. ICC varies with specific device configuration and operating frequency.
3. T_A = 25°C

ispXPLD 5000MX Family Internal Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays													
t_{IN}	Input Buffer Delay	—	—	0.70	—	0.91	—	0.96	—	1.11	—	1.30	ns
t_{GCLK_IN}	Global Clock Input Buffer Delay	—	—	0.40	—	0.35	—	0.35	—	0.35	—	0.55	ns
t_{RST}	Global RESET Pin Delay	—	—	3.77	—	4.24	—	4.71	—	4.71	—	7.07	ns
t_{GOE}	Global OE Pin Delay	—	—	1.98	—	2.66	—	2.34	—	2.87	—	3.27	ns
t_{BUF}	Delay through Output Buffer	—	—	1.16	—	1.30	—	1.45	—	1.60	—	2.17	ns
t_{EN}	Output Enable Time	—	—	2.52	—	2.84	—	3.16	—	3.63	—	4.23	ns
t_{DIS}	Output Disable Time	—	—	1.92	—	2.40	—	2.40	—	2.40	—	3.60	ns
Routing Delays													
t_{ROUTE}	Delay through SRP	—	—	1.95	—	2.06	—	2.34	—	2.24	—	3.66	ns
t_{INREG}	Input Buffer to Macrocell Register Delay	—	—	0.60	—	0.60	—	0.60	—	0.47	—	1.63	ns
t_{PTSA}	Product Term Sharing Array Delay	—	—	0.50	—	0.50	—	0.53	—	0.83	—	1.34	ns
t_{FBK}	Internal Feedback Delay	—	—	0.19	—	0.02	—	0.39	—	0.03	—	0.60	ns
t_{GCLK}	Global Clock Tree Delay	—	—	0.52	—	0.32	—	0.72	—	0.82	—	0.78	ns
t_{BCLK}	Block PT Clock Delay	—	—	0.12	—	0.14	—	0.15	—	0.15	—	0.23	ns
t_{PTCLK}	Macrocell PT Clock Delay	—	—	0.12	—	0.14	—	0.15	—	0.15	—	0.23	ns
t_{PLL_DELAY}	Programmable PLL Delay Increment	—	—	0.30	—	0.30	—	0.30	—	0.30	—	0.30	ns
t_{BSR}	Block PT Reset Delay	—	—	0.72	—	0.81	—	0.90	—	0.94	—	1.35	ns
t_{PTSR}	Macrocell PT Set/ Reset Delay	—	—	0.60	—	0.75	—	0.75	—	0.75	—	1.13	ns
t_{LPTOE}	Macrocell PT OE Delay	—	—	0.83	—	1.19	—	1.04	—	1.52	—	1.31	ns
t_{SPTOE}	Segment PT OE Delay	—	—	0.83	—	1.19	—	1.04	—	1.52	—	1.31	ns
t_{OSA}	Output Sharing Array Delay	—	—	0.80	—	0.90	—	1.00	—	1.00	—	1.50	ns
t_{PTOE}	Global PT OE Delay	—	—	0.83	—	1.04	—	1.04	—	1.04	—	1.56	ns
t_{PDB}	5-PT Bypass Propagation Delay	—	—	0.20	—	0.23	—	0.25	—	0.25	—	0.38	ns
t_{PDI}	Macrocell Propagation Delay	—	—	0.50	—	0.93	—	0.72	—	0.72	—	1.04	ns

ispXPLD 5000MX Family Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Base Parameter	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{CASC}	Additional Delay for PT Cascading between MFBs	—	—	0.71	—	0.80	—	0.89	—	0.92	—	1.33	ns
$t_{CICOMFB}$	Carry Chain Delay, MFB to MFB	—	—	0.35	—	0.39	—	0.44	—	0.46	—	0.66	ns
t_{CICOMC}	Carry Chain Delay, Macro-Cell to Macro-Cell	—	—	0.10	—	0.11	—	0.13	—	0.13	—	0.19	ns
t_{FLAG}	Routing Delay for Extended Function Flags	—	—	2.62	—	2.94	—	3.27	—	3.40	—	4.91	ns
$t_{FLAGEXP}$	Additional Flag Delay when Expanding Data Widths	$t_{FLAGFULL}$, $t_{FLAGAFULL}$, $t_{FLAGEMPTY}$, $t_{FLAGAEMPTY}$	—	2.57	—	2.89	—	3.21	—	3.34	—	4.82	ns
t_{SUM}	Counter Sum Delay	t_{PTSA}	—	0.80	—	0.90	—	1.00	—	1.04	—	1.50	ns
Optional Adjusters													
t_{BLA}	Block Loading Adder	t_{ROUTE}	—	0.04	—	0.04	—	0.05	—	0.05	—	0.07	ns
t_{EXP}	PT Expander Adder	t_{ROUTE}	—	0.53	—	0.60	—	0.66	—	0.69	—	0.99	ns
t_{INDIO}	Additional Delay for the Input Register	t_{INREG}	—	0.50	—	0.56	—	0.63	—	0.65	—	0.94	ns
$t_{PLL\_SEC\_DELAY}$	Secondary PLL Output Delay	t_{PLL_DELAY}	—	0.91	—	0.91	—	0.91	—	0.91	—	0.91	ns
t_{INEXP}	MFB Input Extender	t_{ROUTE}	—	0.62	—	0.70	—	0.78	—	0.81	—	1.16	ns
Input and Output Buffer Delays													
t_{IOI}	Input Buffer Selection Adder	t_{GCLK_IN}, t_{IN}, t_{GOE}, t_{RST}	Refer to sysIO Adjuster Tables										ns
t_{IOO}	Output Buffer Selection Adder	t_{BUF}											ns
FIFO													
$t_{FIFOWCLKS}$	Write Data Setup before Write Clock Time	—	-0.27	—	-0.27	—	-0.22	—	-0.22	—	-0.21	—	ns
$t_{FIFOWCLKH}$	Write Data Hold after Write Clock Time	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	-0.01	—	ns
$t_{FIFOCLKSKEW}$	Opposite Clock Cycle Delay	—	—	1.40	—	1.40	—	1.76	—	1.76	—	1.83	ns
$t_{FIFOFULL}$	Write Clock to Full Flag Delay	—	—	3.08	—	3.08	—	3.85	—	3.85	—	4.00	ns
$t_{FIFOAFULL}$	Write Clock to Almost Full Flag Delay	—	—	3.08	—	3.08	—	3.86	—	3.86	—	4.01	ns
$t_{FIFOEMPTY}$	Read Clock to Empty Flag Delay	—	—	3.08	—	3.08	—	3.86	—	3.86	—	4.01	ns
$t_{FIFOAEMPTY}$	Read Clock to Almost Empty Flag Delay	—	—	3.08	—	3.08	—	3.86	—	3.86	—	4.01	ns

Power Estimation Equations

ICC = ICC_DC + IMFB_CPLD + IMFB_ SRAM/PDPRAM/FIFO + IMFB_DPRAM + IMFB_CAM + IPLL_D

ICC_DC
Use the appropriate value for 5000MC (1.8V power supply) or 5000MV/B (2.5V/3.3V power supply) from the data sheet.

IMFB_CPLD
= ((**K0** * CPLD MFB inputs + **K1** * CPLD Logical Product Terms + **K2** * CPLD GRP from MFB + **K3** * CPLD GRP from IFB) * AF+ **K4**) * FREQ / 1000µA/mA

IMFB_CAM
= CAM Memory MFBs * ((FREQ * **K8**) + **K9**) (CAM operating in typical mode)

IMFB_ SRAM/PDPRAM/FIFO
= (WR_ PERCENT * (**K1** + WR_ PERCENT * 8 * **K0** + **K10** + **K11**) + RD_ PERCENT * (**K1** + 128 * RD_PERCENT * **K0** + 8 * OSW_PERCENT * **K2**)) * SRAM/PDPRAM/FIFO Memory MFBs * FREQ / 1000µA/mA

IMFB_ DPRAM
= (WR_ PERCENT * (2 * **K1** + 2 * WR_ PERCENT * 8 * **K0** + **K10** + **K11**) + RD_ PERCENT * (2 * **K1** + 2 * 128 * RD_PERCENT * **K0** + 8 * OSW_PERCENT * **K2**)) * DPRAM Memory MFBs * FREQ / 1000µA/mA

IPLL_D
= **K5** * PLL_FREQ * number of PLLs used. IPPL_D is the PLL digital component of the VCC supply current.

Analog portion of PLL supply current consumption, from PLL power pin:

IPLL_A = (**K6** * PLL_FREQ + **K7**) * number of PLLs used

Notes:

- ICC = Current consumption of VCC power supply (mA)
- ICC-DC = ICC DC component – Current consumption at 0Mhz (mA)
- IMFB_CPLD = CPLD (non-memory logic) current consumption (mA)
- IMFB_SRAM/PDPRAM/FIFO = Current consumption for SRAM, PDPRAM, and FIFO (mA)
- IMFB_DPRAM = Current consumption for DPRAM (mA)
- IMFB_CAM = Current consumption for CAM (mA)
- IPLL_D = PLL Current consumption of digital VCC power supply (mA)
- IPLL_A = PLL analog power pin current consumption (VCCP pin)

Signals	208 PQFP[4]	256 fpBGA[3, 5]	484 fpBGA, 5[3]	672 fpBGA[3, 5]
VCC	10, 49, 76, 114, 153, 180	D4, D13, F6, F11, L6, L11, N4, N13	A17, A6, AA2, AA21, AB17, AB6, B2, B21, D19, D4, F1, F22, G10, G11, G12, G13, K16, K7, L16, L7, M16, M7, T10, T11, T12, T13, T14, T9, U1, U22, W19, W4	AA21, AA6, F21, F6, G20, G7, J13, J14, K13, K14, L13, L14, M13, M14, N10, N11, N12, N15, N16, N17, N18, N9, P10, P11, P12, P15, P16, P17, P18, P9, R13, R14, T13, T14, U13, U14, V13, V14, Y20, Y7
VCCO0	5, 17, 189, 204	A1, F7, G6	B9, C3, G8, G9, H7, J2, J7, P4	H10, H11, H8, H9, J8, J9, K8, L8, M8, N8
VCCO1	42, 57, 72	K6, L7, T1	AA9, R7, T3, T8, Y3	P8, R8, T8, U8, V8, V9, W10, W11, W8, W9
VCCO2	85, 100, 107, 121	K11, L10, T16	AA14, R16, T15, T20, Y20	P19, R19, T19, U19, V18, V19, W12, W13, W14, W15, W16, W17, W18, W19
VCCO3	146, 161, 176	A16, F10, G11	B14, C20, G14, G15, H16, J16, J21, P19	H12, H13, H14, H15, H16, H17, H18, H19, J18, J19, K19, L19, M19, N19
VCCP	136	J16	M22	N25
VCCJ	27	J1	M1	N4
GND	15, 29, 44, 81, 119, 148, 185, 7, 19, 191, 205, 40, 56, 70, 87, 101, 109, 123, 144, 160, 174	K1, C3, C14, E5, E12, G7, G8, G9, G10, H7, H8, H9, H10, J7, J8, J9, J10, K7, K8, K9, K10, M5, M12, P3	N1, A1, A2, A21, A22, AA1, AA22, AB1, AB22, B1, B22, C15, C8, D11, D12, E18, E5, F17, F6, G16, G7, H10, H11, H12, H13, H14, H15, H20, H3, H8, H9, J10, J11, J12, J13, J14, J15, J8, J9, K10, K11, K12, K13, K14, K15, K8, K9, L10, L11, L12, L13, L14, L15, L19, L4, L8, L9, M10, M11, M12, M13, M14, M19, M4, M9, N10, N11, N12, N13, N14, N9, P10, P11, P12, P13, P14, P9, R10, R11, R12, R13, R14, R15, R8, R9, T16, T7, W11, W12, Y15, Y8	A11, A16, A2, A25, AE1, AE2, AE25, AE26, AF11, AF16, AF2, AF25, B1, B2, B25, B26, J10, J11, J12, J15, J16, J17, K10, K11, K12, K15, K16, K17, K18, K9, L1, L10, L11, L12, L15, L16, L17, L18, L26, L9, M10, M11, M12, M15, M16, M17, M18, M9, N13, N14, P13, P14, R10, R11, R12, R15, R16, R17, R18, R9, T1, T10, T11, T12, T15, T16, T17, T18, T26, T9, U10, U11, U12, U15, U16, U17, U18, U9, V10, V11, V12, V15, V16, V17
GNDP	134	K16	N22	P26
NC[2]	—	**5256MX**: A2, A11, A12, A15, B2, B12, B15, B16, C4, C12, C15, C16, D1, D11, D14, D15, D16, E1, E4, E10, E11, E13, E14, F4, F5, F12, F13, L1, L4, M3, M7, M13, N2, N6, P1, P2, P5, P6, P13, P14, P15, P16, R1, R2, R4, R5, R6, R16, T2, T3, T4, T5, T6 **5512MX/5768MX**: L1	**5512MX**: P1, AA19, AB2, AB21, J17, J6, K1, K17, K18, K19, K2, K20, K21, K22, K3, K4, K5, K6, L1, L17, L18, L2, L20, L21, L22, L3, L5, L6, M15, M17, M18, M2, M20, M21, M3, M5, M6, M8, N15, N17, N18, N19, N2, N20, N21, N3, N4, N5, N6, N8, P15, P17, P18, P2, P21, P22, P5, P6, P8, U17, U6, V18, V5, W6 **5768MX/51024MX**: None	A12, A13, A14, A15, AA10, AA11, AA12, AA13, AA14, AA15, AA16, AA17, AA7, AB10, AB11, AB12, AB13, AB14, AB15, AB16, AB17, AC10, AC11, AC12, AC13, AC14, AC15, AC16, AC17, AD11, AD12, AD13, AD14, AD15, AD16, AE11, AE12, AE13, AE14, AE15, AE16, AF12, AF13, AF14, AF15, B11, B12, B13, B14, B15, B16, C11, C12, C13, C14, C15, C16, C3, D10, D11, D12, D13, D14, D15, D16, D17, E10, E11, E12, E13, E14, E15, E16, E17, E6, E7, E8, F10, F11, F12, F13, F14, F15, F16, F17, G10, G11, G12, G13, G14, G15, G16, G17, Y10, Y11, Y12, Y13, Y14, Y15, Y16, Y17

1. All grounds must be electrically connected at the board level.
2. NC pins should not be connected to any active signals, V_{CC} or GND.
3. Balls for GND, V_{CC} and V_{CCOX} are connected within the substrate to their respective common signals. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
4. Pin orientation follows the conventional counter-clockwise order from pin 1 marking of the topside view.
5. Internal GNDs and I/O GNDs (Bank 0 - Bank 3)pare connected inside package. V_{CCO} balls connect to four power planes within the package, one each for V_{CCOX}.

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
3	76P	L30/PLL_FBK1	L0	J0	L31	F15	E21
3	77N	M0/PLL_RST1	P27	N27	M1	H12	G22
3	77P	M2	P26	N26	M3	G14	F21
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	78N	M4	P25	N25	M5	F16	H21
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	78P	M6	P24	N24	-	E16	G21
-	-	GND	-	-	-	GND	GND
3	79N	M8	P23	N23	M9	G13	D22
3	79P	M10	P22	N22	M11	G12	D21
3	80N	M12	P21	N21	M13	F14	J20
3	80P	M14/CLK_OUT1	P20	N20	M15	E15	J19
3	81N	M16	N31	-	M17	F12	E20
-	-	VCC	-	-	-	VCC	VCC
3	81P	M18	N30	M30	M19	F13	F20
3	82N	M20	N29	M28	M21	D16	H17
3	82P	M22	N28	M26	M23	D15	H18
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	83N	M24	N27	-	M25	—	J18
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	83P	M26	N26	-	M27	—	H19
3	84N	M28	N25	-	M29	—	G20
3	84P	M30	N24	-	M31	—	G19
-	-	GND	-	-	-	GND	GND
3	85N	N0	N23	-	N1	—	C22
-	-	VCC	-	-	-	VCC	VCC
3	85P	N2	N22	-	N3	—	C21
3	86N	N4	N21	-	-	—	D20
3	86P	N6	N20	-	-	—	C19
3	87N	N8	N19	-	N9	C16	F19
3	87P	N10	N18	-	N11	B16	E19
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	88N	N12	N17	-	N13	C15	G18
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	88P	N14	N16	-	N15	B15	F18
3	89N	N16	N15	-	N17	E14	B20
3	89P	N18	N14	-	N19	D14	B19
3	90N	N20	N13	-	N21	E13	A20
3	90P	N22	N12	-	N23	A15	A19
3	91N	N24	P19	N19	N25	D12	D18
3	91P	N26	P18	N18	N27	B14	C18
3	92N	N28	P17	N17	N29	C13	G17
3	92P	N30	P16	N16	N31	A14	F16

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	VCC	-	-	-	VCC	VCC
0	109P	Q28	Q30	S30	Q29	A7	C11
-	-	GND	-	-	-	GND	GND
0	110N	Q26	Q29	S29	Q27	D7	B11
0	110P	Q24	Q28	S28	Q25	C7	A11
0	111N	Q22	Q27	S27	Q23	B6	F11
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	111P	Q20	Q26	S26	Q21	E7	F10
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	112N	Q18	Q25	S25	Q19	E6	E10
0	112P	Q16	Q24	S24	Q17	A6	C10
0	113N	Q14/VREF0	Q3	S3	Q15	A5	D10
0	113P	Q12	Q2	S2	Q13	A4	B10
0	114N	Q10	Q23	S23	Q11	B5	A10
0	114P	Q8	Q22	S22	Q9	A3	A9
0	115N	Q6	Q21	S21	Q7	B4	C9
0	115P	Q4	Q20	S20	Q5	B3	D9
0	116N	Q2	Q19	S19	Q3	C5	F9
0	116P	Q0	Q18	S18	Q1	C6	E9
0	117N	R30	Q1	S1	R31	D5	A8
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	117P	R28	Q0	S0	R29	D6	B8
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	118N	R26	S29	-	R27	—	A7
0	118P	R24	S28	-	R25	—	B7
0	119N	R22	S27	-	R23	—	A5
0	119P	R20	S26	-	R21	—	B5
0	120N	R18	S25	-	R19	—	B6
0	120P	R16	S24	-	R17	—	C7
0	121N	R14	S23	-	R15	—	E8
0	121P	R12	S22	-	R13	—	E7
0	122N	R10	S21	-	R11	—	E6
-	-	VCC	-	-	-	VCC	VCC
0	122P	R8	S20	-	R9	—	D6
-	-	GND	-	-	-	GND	GND
0	123N	R6	S19	-	R7	—	D8
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	123P	R4	S18	-	R5	—	F8
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	124N	R2	S17	-	R3	—	F7
0	124P	R0	S16	-	R1	—	D7
0	125N	S30	S15	-	S31	A2	C6
0	125P	S28	S14	-	S29	B2	C5

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
0	126N	S26	S13	-	S27	—	C4
0	126P	S24	S12	-	S25	—	D5

Global Clock LVDS pair options: GCLK0 and GCLK1, as well as GCLK2 and GCLK3, can be paired together to receive differential clocks; where GCLK0 and GCLK3 are the positive LVDS inputs.

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	TCK	-	-	-	T1	P3
-	-	TDO	-	-	-	V1	P2
1	0P	A30	A0	C0	A31	—	P1
1	0N	A28	A1	C1	A29	—	R1
1	1P	A26	A2	C2	A27	—	P6
1	1N	A24	A3	C3	A25	—	R6
1	2P	A22	A4	C4	A23	—	P7
1	2N	A20	A5	C5	A21	—	R7
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	3P	A18	A6	C6	A19	—	R4
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	3N	A16	A7	C7	A17	—	R5
-	-	GND	-	-	-	GND	GND
1	4P	A14	A8	C8	A15	—	R3
-	-	VCC	-	-	-	VCC	VCC
1	4N	A12	A9	C9	A13	—	R2
1	5P	A10	A10	C10	A11	—	T2
1	5N	A8	A11	C11	A9	—	T3
1	6P	A6	A12	C12	A7	—	T4
1	6N	A4	A13	C13	A5	—	T5
1	7P	A2	A14	C14	A3	—	U2
1	7N	A0	A15	C15	A1	—	U3
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	8P	C30	A16	C16	C31	—	U4
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	8N	C28	A17	C17	C29	—	U5
1	9P	C26	A18	C18	C27	—	T6
1	9N	C24	A19	C19	C25	—	U6
1	10P	C22	A20	C20	C23	—	T7
1	10N	C20	A21	C21	C21	—	U7
1	11P	C18	A22	C22	C19	—	U1
1	11N	C16	A23	C23	C17	—	V1
1	12P	C14	A24	C24	C15	—	V2
1	12N	C12	A25	C25	C13	—	V3
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	13P	C10	A26	C26	C11	—	V5
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	13N	C8	A27	C27	C9	—	V4
-	-	GND	-	-	-	GND	GND
1	14P	C6	A28	C28	C7	—	W2
-	-	VCC	-	-	-	VCC	VCC
1	14N	C4	A29	C29	C5	—	W3
1	15P	C2	A30	C30	C3	—	W4

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	31P	G26	H16	-	G27	V6	AB7
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	31N	G24	H18	-	G25	V7	AC7
-	-	GND	-	-	-	GND	GND
1	32P	G22	H20	-	G23	Y5	AB6
-	-	VCC	-	-	-	VCC	VCC
1	32N	G20	H22	-	G21	AA5	AC6
1	33P	G18	-	-	G19	Y6	AC8
1	33N	G16	-	-	G17	Y7	AC9
1	34P	G14	-	-	G15	AA6	AC5
1	34N	G12	-	-	G13	AA7	AD4
1	35P	G10	-	-	G11	W7	AD5
1	35N	G8	-	-	G9	V8	AD6
1	36P	G6	-	-	G7	W8	AD7
1	36N	G4	-	-	G5	U9	AD8
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
-	-	CFG0	-	-	-	U10	AE3
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	37P	G0	G16	E16	G1	AB7	AD9
1	37N	H30	G17	E17	H31	AA8	AD10
1	38P	H28	G18	E18	H29	AB8	AE4
1	38N	H26	G19	E19	H27	AB9	AE5
1	39P	H24	G20	E20	H25	W9	AE6
1	39N	H22	G21	E21	H23	Y9	AE7
1	40P	H20	G22	E22	H21	AB10	AE8
1	40N	H18	G23	E23	H19	AA10	AE9
1	-	H16/VREF1	-	-	H17	W10	AE10
1	41P	H14	G24	E24	H15	Y10	AF3
1	41N	H12	G25	E25	H13	Y11	AF4
-	-	GND (Bank 1)	-	-	-	GND (Bank 1)	GND (Bank 1)
1	42P	H10	G26	E26	H11	V9	AF5
-	-	VCCO1	-	-	-	VCCO1	VCCO1
1	42N	H8	G27	E27	H9	V10	AF6
1	43P	H6	G28	E28	H7	AA11	AF7
-	-	GND	-	-	-	GND	GND
1	43N	H4	G29	E29	H5	AB11	AF8
-	-	VCC	-	-	-	VCC	VCC
1	44P	H2	G30	E30	H3	U11	AF9
1	44N	H0	G31	E31	H1	V11	AF10
2	45P	I0	J0	L0	I1	AB12	AF17
-	-	VCC	-	-	-	VCC	VCC
2	45N	I2	J1	L1	I3	AA12	AF18

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
0	142N	Y26	Y29	AA29	Y27	B11	A10
0	142P	Y24	Y28	AA28	Y25	A11	A9
0	143N	Y22	Y27	AA27	Y23	F11	A8
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	143P	Y20	Y26	AA26	Y21	F10	A7
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	144N	Y18	Y25	AA25	Y19	E10	A6
0	144P	Y16	Y24	AA24	Y17	C10	A5
0	145N	Y14/VREF0	Y3	AA3	Y15	D10	A4
0	145P	Y12	Y2	AA2	Y13	B10	A3
0	146N	Y10	Y23	AA23	Y11	A10	B10
0	146P	Y8	Y22	AA22	Y9	A9	B9
0	147N	Y6	Y21	AA21	Y7	C9	B8
0	147P	Y4	Y20	AA20	Y5	D9	B7
0	148N	Y2	Y19	AA19	Y3	F9	B6
0	148P	Y0	Y18	AA18	Y1	E9	B5
0	149N	Z30	Y1	AA1	Z31	A8	B4
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	149P	Z28	Y0	AA0	Z29	B8	B3
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	150N	Z26	AA29	-	Z27	A7	C10
0	150P	Z24	AA28	-	Z25	B7	C9
0	151N	Z22	AA27	-	Z23	A5	C8
0	151P	Z20	AA26	-	Z21	B5	C7
0	152N	Z18	AA25	-	Z19	B6	C6
0	152P	Z16	AA24	-	Z17	C7	C5
0	153N	Z14	AA23	-	Z15	E8	C4
0	153P	Z12	AA22	-	Z13	E7	D5
0	154N	Z10	AA21	-	Z11	E6	D9
-	-	VCC	-	-	-	VCC	VCC
0	154P	Z8	AA20	-	Z9	D6	D8
-	-	GND	-	-	-	GND	GND
0	155N	Z6	AA19	-	Z7	D8	D7
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	155P	Z4	AA18	-	Z5	F8	D6
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	156N	Z2	AA17	-	Z3	F7	F9
0	156P	Z0	AA16	-	Z1	D7	E9
0	157N	AA30	AA15	-	AA31	C6	F7
0	157P	AA28	AA14	-	AA29	C5	F8
0	158N	AA26	AA13	-	AA27	C4	G8
0	158P	AA24	AA12	-	AA25	D5	G9

Global Clock LVDS pair options: GCLK0 and GCLK1, as well as GCLK2 and GCLK3, can be paired together to receive differential clocks; where GCLK0 and GCLK3 are the positive LVDS inputs.

ispXPLD 5000MB (2.5V) Industrial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MB	LC5256MB-5F256I	256	2.5	5.0	fpBGA	256	141	I
	LC5256MB-75F256I	256	2.5	7.5	fpBGA	256	141	I
LC5512MB	LC5512MB-75Q208I	512	2.5	7.5	PQFP	208	149	I
	LC5512MB-75F256I	512	2.5	7.5	fpBGA	256	193	I
	LC5512MB-75F484I	512	2.5	7.5	fpBGA	484	253	I
LC5768MB	LC5768MB-75F256I	768	2.5	7.5	fpBGA	256	193	I
	LC5768MB-75F484I	768	2.5	7.5	fpBGA	484	317	I
LC51024MB	LC51024MB-75F484I	1024	2.5	7.5	fpBGA	484	317	I
	LC51024MB-75F672I	1024	2.5	7.5	fpBGA	672	381	I

ispXPLD 5000MV (3.3V) Commercial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MV	LC5256MV-4F256C	256	3.3	4.0	fpBGA	256	141	C
	LC5256MV-5F256C	256	3.3	5.0	fpBGA	256	141	C
	LC5256MV-75F256C	256	3.3	7.5	fpBGA	256	141	C
LC5512MV	LC5512MV-45Q208C	512	3.3	4.5	PQFP	208	149	C
	LC5512MV-75Q208C	512	3.3	7.5	PQFP	208	149	C
	LC5512MV-45F256C	512	3.3	4.5	fpBGA	256	193	C
	LC5512MV-75F256C	512	3.3	7.5	fpBGA	256	193	C
	LC5512MV-45F484C	512	3.3	4.5	fpBGA	484	253	C
	LC5512MV-75F484C	512	3.3	7.5	fpBGA	484	253	C
LC5768MV	LC5768MV-5F256C	768	3.3	5.0	fpBGA	256	193	C
	LC5768MV-75F256C	768	3.3	7.5	fpBGA	256	193	C
	LC5768MV-5F484C	768	3.3	5.0	fpBGA	484	317	C
	LC5768MV-75F484C	768	3.3	7.5	fpBGA	484	317	C
LC51024MV	LC51024MV-52F484C	1024	3.3	5.2	fpBGA	484	317	C
	LC51024MV-75F484C	1024	3.3	7.5	fpBGA	484	317	C
	LC51024MV-52F672C	1024	3.3	5.2	fpBGA	672	381	C
	LC51024MV-75F672C	1024	3.3	7.5	fpBGA	672	381	C

ispXPLD 5000MV (3.3V) Industrial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MV	LC5256MV-5F256I	256	3.3	5.0	fpBGA	256	141	I
	LC5256MV-75F256I	256	3.3	7.5	fpBGA	256	141	I
LC5512MV	LC5512MV-75Q208I	512	3.3	7.5	PQFP	208	149	I
	LC5512MV-75F256I	512	3.3	7.5	fpBGA	256	193	I
	LC5512MV-75F484I	512	3.3	7.5	fpBGA	484	253	I
LC5768MV	LC5768MV-75F256I	768	3.3	7.5	fpBGA	256	193	I
	LC5768MV-75F484I	768	3.3	7.5	fpBGA	484	317	I
LC51024MV	LC51024MV-75F484I	1024	3.3	7.5	fpBGA	484	317	I
	LC51024MV-75F672I	1024	3.3	7.5	fpBGA	672	381	I

ispXPLD 5000MV (3.3V) Lead-Free Commercial Devices (Continued)

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5512MV	LC5512MV-45QN208C	512	3.3	4.5	Lead-free PQFP	208	149	C
	LC5512MV-75QN208C	512	3.3	7.5	Lead-free PQFP	208	149	C
	LC5512MV-45FN256C	512	3.3	4.5	Lead-free fpBGA	256	193	C
	LC5512MV-75FN256C	512	3.3	7.5	Lead-free fpBGA	256	193	C
	LC5512MV-45FN484C	512	3.3	4.5	Lead-free fpBGA	484	253	C
	LC5512MV-75FN484C	512	3.3	7.5	Lead-free fpBGA	484	253	C
LC5768MV	LC5768MV-5FN256C	768	3.3	5.0	Lead-free fpBGA	256	193	C
	LC5768MV-75FN256C	768	3.3	7.5	Lead-free fpBGA	256	193	C
	LC5768MV-5FN484C	768	3.3	5.0	Lead-free fpBGA	484	317	C
	LC5768MV-75FN484C	768	3.3	7.5	Lead-free fpBGA	484	317	C
LC51024MV	LC51024MV-52FN484C	1024	3.3	5.2	Lead-free fpBGA	484	317	C
	LC51024MV-75FN484C	1024	3.3	7.5	Lead-free fpBGA	484	317	C
	LC51024MV-52FN672C	1024	3.3	5.2	Lead-free fpBGA	672	381	C
	LC51024MV-75FN672C	1024	3.3	7.5	Lead-free fpBGA	672	381	C

ispXPLD 5000MV (3.3V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MV	LC5256MV-5FN256I	256	3.3	5.0	Lead-free fpBGA	256	141	I
	LC5256MV-75FN256I	256	3.3	7.5	Lead-free fpBGA	256	141	I
LC5512MV	LC5512MV-75QN208I	512	3.3	7.5	Lead-free PQFP	208	149	I
	LC5512MV-75FN256I	512	3.3	7.5	Lead-free fpBGA	256	193	I
	LC5512MV-75FN484I	512	3.3	7.5	Lead-free fpBGA	484	253	I
LC5768MV	LC5768MV-75FN256I	768	3.3	7.5	Lead-free fpBGA	256	193	I
	LC5768MV-75FN484I	768	3.3	7.5	Lead-free fpBGA	484	317	I
LC51024MV	LC51024MV-75FN484I	1024	3.3	7.5	Lead-free fpBGA	484	317	I
	LC51024MV-75FN672I	1024	3.3	7.5	Lead-free fpBGA	672	381	I

For Further Information

In addition to this data sheet, the following technical notes may be helpful when designing with the ispXPLD 5000MX family:

- TN1000 – sysIO Usage Guidelines for Lattice Devices
- TN1003 – sysCLOCK PLL Usage Guide for ispXPGA, ispGDX2, ispXPLD and ispMACH 5000VG Devices
- TN1031 – Power Estimation in ispXPLD 5000MX Devices
- TN1030 – Using Memory in ispXPLD 5000MX Devices
- TN1026 – ispXP Configuration Usage Guidelines